## IN THE SPECIFICATION:

Please insert the following paragraph at the beginning of the specification.

This application is a 371 of international application PCT/JP2004/004182, which claims priority based on Japanese patent application Nos. 2003-101226 filed April 4, 2003, and 2003-186632 filed June 30, 2003, which are incorporated herein by reference.

Please replace the paragraph beginning on page 10, line 9, with the following rewritten paragraph:

In this invention, the solvent containing an ester structure is preferably used, and a solvent containing a lactone structure is more preferable. The most preferable solvent is  $\gamma$ -butyrolactone. The boiling point used in this invention is the boiling point under one atmospheric pressure, i.e., the pressure of  $\frac{1.013 \times 105 \text{ N/m}^2}{1.013 \times 10^5 \text{ N/m}^2}$ . Although the measurement of boiling point can be done by a well-known technique and it is not especially limited, it can be measured by using, for example, the boiling point meter of Swietoslawski.

Please replace the paragraph beginning on page 26, line 22,

with the following rewritten paragraph:

(2) Supposing the weight of substrate as W1, the weight of [[glass]] substrate and the dielectric composition as W2, the density of the dielectric composition as D, and the volume as V, the dielectric composition, D = (W2-W1)/V.

Please replace the paragraph beginning on page 37, line 11, with the following rewritten paragraph:

Except that the solvent was propylene glycol monomethyl monomethylether acetate, a paste composition D-3 was prepared in the same way as that of the paste composition C-2. The boiling point of propylene glycol monomethyl acetate is 146°C. Then, according to the method of Example 1, a high dielectric constant composition was prepared and the result of evaluation of its dielectric characteristics is shown in Table 4. The relative dielectric constant was 46, the dielectric loss tangent was 4.7%, and the capacitance per area was 2.7 nF/cm², and was inferior in the electrical property. The porosity was 35 volume%.

Please replace the paragraph beginning on page 49, line 9, with the following rewritten paragraph:

A barium titanate filler (BT-05 of SAKAI CHEMICAL INDUSTRY

Co., Ltd., mean particle diameter: 0.5 µm) 6067 weight parts, a barium strontium titanate filler (HPS-2000 of TPL. Inc., mean particle diameter: 0.045 µm) 1613 weight parts,  $\gamma$ -butyrolactone 1523 weight parts and a dispersant (a copolymer having an acid group with a phosphoric-ester skeleton: BYK-W9010 of BYK-Chemie Japan KK) 77 weight parts were mixed and dispersed under ice-cooling for 1 hour using a homogenizer, and a dispersion liquid X-7 was obtained.

Please replace the paragraph beginning on page 52, line 14, with the following rewritten paragraph:

The epoxy resin ("Phenolite" EPPN-502H of NIPPON KAYAKU CO., LTD.) 400 weight parts, a phenol novolak resin (TD-2131 of DAINIPPON INK AND CHEMICALS, Inc.) 400 weight parts and y-butyrolactone 1000 weight parts were mixed and the resin solution Y-1 was obtained.

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Table 1 beginning on page 63 has been amended as follows:

	Paste co	Paste composition	u					Dielectr MHz)	cic Chara	Dielectric Characteristics (1 MHz)	cs (1	Film Charac terist ic
Exampl e	Inorga nic filler	Resin	Curing agent	Solven t	Additi ve agent	Content to for the inorganic . filler in the solid content t	conten t of the solven t in the paste (wt%)	Thickn ess . (µm)	Releat ive dielec tric consta nt	Capaci tance (nF/cm <sup>2</sup> )	Dieelc tric loss tangen t (%)	Porosi ty (volum e %)
1	Barium Titana te SAKAI CHEMIC AL BT- 05	Epoxy resin NIPPON KAYAKU EPPN50 2H	Phenol Novola k resin DAINIP PON INK	Y- butyro lacton e	triphe nylpho sphine	94	10	10	88	7.3	2.8	თ

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12	14	20
3.4	3.0	3.2
4.3	88	6.4
73		58
15	10	8
15	20	25
94	94	94
triphe nylpho sphine	triphe nylpho sphine	triphe nylpho sphine
Y- butyro lacton e	γ- butyro lacton e	Y- butyro lacton e
Phenol Novola k resin DAINIP PON INK	Phenol Novola k . resin . DAINIP PON INK	Phenol Novola k resin DAINIP PON INK
Epoxy resin NIPPON KAYAKU EPPN50 2H	Epoxy resin NIPPON KAYAKU EPPN50 2H	Epoxy resin NIPPON KAYAKU EPPN50 2H
Barium Titana te SAKAI CHEMIC AL BT- 05	Barium Titana te SAKAI CHEMIC AL BT- 05	Barium Titana te SAKAI CHEMIC AL BT- 05
2	က	4

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G		. 7		26
3.6		3.1		4.6
11.3		8.4		5.3
102		95		58
ω		10		10
10		15		15
94		94		94
triphe nylpho sphine	BYK- W903	triphe nylpho sphine	BYK- W903	triphe nylpho sphine
Y- butyro lacton e		Y- butyro lacton e		N-methy 1-2- pyrrol idone
Phenol Novola k resin	DAINIP PON INK TD2131		DAINIP PON INK TD2131	Phenol Novola k resin DAINIP PON INK
Epoxy resin NIPPON KAYAKU	EPPN50 2H	Epoxy resin NIPPON KAYAKU	EPPN50 2H	Epoxy resin NIPPON KAYAKU EPPN50 2H
Barium Titana te SAKAI	CHEMIC AL BT- 05	Barium Titana te SAKAI	CHEMIC AL BT- 05	Barium Titana te SAKAI CHEMIC AL BT- 05
S		. 9		7

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Barıum	Fboxy	Fuenor	rcuyle	rribue	7,7	T 2	7.0	64	٠. ر	4·8	17
Titana		Novola	ne	nylpho							
te t	NIPPON	ᅩ	glycol	glycol sphine							
SAKAI	KAYAKU	resin	acetat								
CHEMIC	EPPN50	DAINIP	Þ								
AL BT-	2H	PON	diacet								
05		INK	ate					•			
		TD2131									

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Table 8 on page 72 has been amended as follows:

	Paste comp	composition				8			
	Dispersi on liquid	Inorganic fi	filler				Resin solutio n	Inorganic filler/re sin ratio	Stabilit y of dispersi
		Inorgani c filler composit ion	Mean particle diameter (µm)	Inorgani c filler composit ion.	Mean particle diameter (µm)	Max/Min (ratio)	Epoxy resin	Volume ratio	on liquid
Example 43	X-2	Barium Titanate	0.5	Barium Titanate	090.0	8.3	Y-1	79/21	Stabilit y
Example 44	Y-7	Barium Titanate	0.5	Strontiu m Titanate	0.045	11.1	Y-1	79/21	Stabilit y
Example 45	X-8	Barium Titanate	0.5	Titanium Oxide	0.2	2.5	Y-1	[[81/29]] 81/19	Instabil ity slightly (cohesio n)
Example 46	8-X	Lead type filler	6.0	Barium Titanate	0.059	15.3	Y-1	86/14	Stabilit y

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Comparat ive example 4	t						Y-1	0/100	1
Comparat ive example 5	X-10	Barium Titanate	0.5	1	1	l	Y-1	19/21	Stabilit Y
Comparat ive example 6	X-11	Barium Titanate	٢	Barium Titanate	0.5	14	Y-1	79/21	Instabil ity (filler sediment ation)
Comparat ive example 7	X-12	Barium Titanate	40	Barium Titanate	2.1	19	Y-1	79/21	Instabil ity (filler sediment ation)
Comparat ive example 8	X-13	Barium Titanate	20	Barium Titanate	2.1	9.5	Y-1	79/21	Instabil ity (filler sediment ation)
Comparat ive example 9	ı	Barium Titanate	0.059	Strontiu m Titanate	0.045	1.3	Y-1	79/21	Instabil ity (cohesio n)